Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (original): A method to assemble a pre-curved bolster plate to one side of a substrate having a first side and a second side, comprising:

attaching a component to an electrical contact area on said first side of said substrate; and

attaching said pre-curved bolster plate on said second side of said substrate, wherein said pre-curved bolster plate is attached to said second side opposite said electrical contact area on said first side of said substrate.

Claim 2 (original): The method of claim 1, wherein said component is a land grid array (LGA) component.

Claim 3 (original): The method of claim 1, wherein said substrate is selected from a group of substrates consisting of: a printed circuit board (PCB), a multi-chip module (MCM), and a flexible substrate.

Claim 4 (original): The method of claim 1, wherein said pre-curved bolster plate includes a material selected from the group consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a

carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 5 (original): The method of claim 1, wherein said pre-curved bolster plate has a spherical curvature.

Claim 6 (original): The method of claim 1, wherein said pre-curved bolster plate has a cylindrical curvature.

Claim 7 (original): The method of claim 1, wherein said pre-curved bolster plate has a radius of curvature in excess of 100 inches (254 centimeters).

Claims 8-12 (previously cancelled)

Claims 13-20 (previously cancelled)

Claim 21 (previously presented): A method for providing support to a substrate, the method comprising:

attaching a component to an electrical contact area on a first side of the substrate; and

attaching a pre-curved bolster plate on a second side of the substrate, the pre-curved bolster plate having a pre-calculated radius of curvature prior to attachment to the second side of the substrate.

Claim 22 (previously presented): The method of claim 21, wherein the component comprises a land grid array (LGA) component.

Claim 23 (previously presented): The method of claim 21, wherein the substrate is selected from a group of substrates consisting of: a printed circuit board (PCB), a multi-chip module (MCM), and a flexible substrate.

Claim 24 (previously presented): The method of claim 21, wherein the pre-curved bolster plate includes a material selected from a group consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 25 (previously presented): The method of claim 21, wherein the pre-curved bolster plate has a spherical curvature.

Claim 26 (previously presented): The method of claim 21, wherein the pre-curved bolster plate has a cylindrical curvature.

Claim 27 (previously presented): The method of claim 21, wherein the pre-curved bolster plate has a radius of curvature in excess of approximately 100 inches (254 centimeters).

Claim 28 (previously presented): A substrate support assembly produced in accordance with the method of claim 21.

Claims 29-36 (previously cancelled)

Claim 37 (currently amended): A method for coupling a plate member to an electrical packaging assembly, the method comprising:

providing an electrical packaging assembly;

providing a plate member that is pre-curved;

disposing ~~a~~ the plate member against the electrical packaging assembly;

flexing the plate member towards the electrical packaging assembly to produce a flexed plate member; and

coupling the flexed plate member to the electrical packaging assembly.

Claim 38 (currently amended): The method of Claim 37 wherein said flexing comprises ~~flexing~~ curving opposed ends of the plate member towards a substrate of the electrical packaging assembly.

Claim 39 (currently amended): The method of Claim 37 wherein said flexing comprises ~~flexing~~ curving opposed ends of the plate member towards a substrate of the electrical packaging assembly until the plate member is generally flushed against the substrate.

Claim 40 (previously presented): The method of Claim 37 wherein said electrical packaging assembly comprises an electrical component having a plurality of leads attached to an electrical contact area of a substrate.

Claim 41 (previously presented): The method of Claim 39 wherein said electrical packaging assembly comprises an electrical component having a plurality of leads attached to an electrical contact area of said substrate.

Claim 42 (previously presented): The method of Claim 37 wherein said plate member is stamped to achieve a spherical curvature.

Claim 43 (currently amended): The method of Claim 41 wherein said plate member is stamped to achieve a ~~spherical~~ cylindrical curvature.

Claim 44 (previously presented): The method of Claim 37, wherein said plate member is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 45 (previously presented): The method of Claim 43, wherein said plate member is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 46 (currently amended): A method for assembling a bolster plate to a circuit member, the method comprising:

providing a circuit member;

disposing a curved bolster plate against the circuit member;

~~flexing~~ curving the bolster plate towards the circuit member to ~~produce~~ change the curved bolster plate into a ~~flexed~~ flat bolster plate; and

coupling the ~~flexed~~ flat bolster plate to the circuit member.

Claim 47 (currently amended): The method of Claim 46 wherein said ~~flexing~~ curving comprises ~~flexing~~ curving opposed ends of the bolster plate towards the circuit member.

Claim 48 (currently amended): The method of Claim 46 wherein said ~~flexing~~ curving comprises ~~flexing~~ curving opposed ends of the bolster plate towards the circuit member until the bolster plate is generally flushed against the circuit member.

Claim 49 (previously presented): The method of Claim 46 wherein said circuit member includes an electrical contact area having a plurality of leads attached thereto.

Claim 50 (previously presented): The method of Claim 48 wherein said circuit member includes an electrical contact area having a plurality of leads attached thereto.

Claim 51 (previously presented): The method of Claim 46 wherein said bolster plate is stamped to achieve a spherical curvature.

Claim 52 (currently amended): The method of Claim 50 wherein said bolster plate is stamped to achieve a ~~spherical~~ cylindrical curvature.

Claim 53 (previously presented): The method of Claim 46, wherein said bolster plate is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 54 (previously presented): The method of Claim 52, wherein said bolster plate is fabricated from a material selected from the group of materials consisting of: a stainless steel alloy, a powder-coated spring steel alloy, a plated spring steel alloy, a painted spring steel alloy, a titanium steel alloy, a carbon steel alloy, a magnesium alloy, and an aluminum alloy.

Claim 55 (previously presented): An assembly produced in accordance with the method of claim 46.

Claim 56 (new): The method of claim 1, wherein the pre-curved bolster plate has a radius of curvature.

Claim 57 (new): The method of claim 56, wherein the radius of curvature is pre-calculated.

Claim 58 (new): The method of claim 57, wherein the radius of curvature is pre-calculated such that the pre-curved bolster plate deflects into a flat plate after a clamping force is applied to the component which is assembled on the substrate and to the pre-curved bolster plate which is assembled on the substrate.

Claim 59 (new): The method of claim 1, wherein the pre-curved bolster plate has an entire surface that is in contact with the substrate when a clamping force is applied to the pre-curved bolster plate and to the substrate.

Claim 60 (new): The method of claim 1, further comprising:

clamping the component and the bolster plate to the substrate.

Claim 61 (new): The method of claim 1, further comprising:

clamping the component and the bolster plate to the substrate by use of a clamp.

Claim 62 (new): The method of claim 1, further comprising:

clamping the component and the bolster plate to the substrate by bolting a clamp to the substrate.

Claim 63 (new): The method of claim 1, further comprising:

clamping the component to the substrate by bolting a clamp to the substrate by use of a bolt and a spring.

Claim 64 (new): An assembly produced in accordance with the method of claim 1.

Claim 65 (new): The method of claim 21, wherein the radius of curvature is pre-calculated such that the pre-curved bolster plate deflects into a flat plate after a clamping force is applied to the component which is assembled on the substrate and to the pre-curved bolster plate which is assembled on the substrate.

Claim 66 (new): The method of claim 37, wherein the plate member has a radius of curvature.

Claim 67 (new): The method of claim 66, wherein the radius of curvature is pre-calculated.

Claim 68 (new): The method of claim 67, wherein the radius of curvature is pre-calculated such that the plate member deflects into the flat plate member after a clamping force is applied to the electrical packaging assembly and to the plate member which is assembled on the electrical packaging assembly.

Claim 69 (new): The method of claim 46, wherein the curved bolster plate has a radius of curvature.

Claim 70 (new): The method of claim 69, wherein the radius of curvature is pre-calculated.

Claim 71 (new): The method of claim 70, wherein the radius of curvature is pre-calculated such that the curved bolster plate deflects into the flat bolster plate after a clamping force is applied to the circuit member and to the curved bolster plate which is assembled on the circuit member.

Claim 72 (new): The method of claim 46, wherein the curved bolster plate has an entire surface that is in contact with the circuit member when a clamping force is applied to the curved bolster plate and to the circuit member.

Claim 73 (new): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component and the bolster plate to the circuit member.

Claim 74 (new): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component and the bolster plate to the circuit member by use of a clamp.

Claim 75 (new): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component and the bolster plate to the circuit member by bolting a clamp to the circuit member.

Claim 76 (new): The method of claim 46, wherein coupling the flat bolster plate comprises:

clamping a component to the circuit member by bolting a clamp to the circuit member by use of a bolt and a spring.